

Product / Process Change Notice

Parts Affected:

All discrete semiconductor devices manufactured in the SOD-523 package.

Extent of Change:

Copper wire has been added as a qualified material for wire bonding in addition to the currently used gold wire.

Reason for Change:

This change will insure an uninterrupted flow of product and provide increased flexibility for supply chain management.

Effect of Change:

This change does not affect the form, fit, or function of any device. Devices assembled with gold wire will continue to be manufactured concurrently with devices assembled with copper wire.

Qualification:

Standard evaluation and qualifications completed resulting in no performance differences compared to current product.

Effective Date of Change:

January 9, 2013.

Sample Availability:

Please contact Salesperson or Manufacturer's Representative.

Part Numbers Affected:

CEN1175	CMOZ10L	CMOZ2V4	CMOZ30L	CMOZ6L8
CEN1230	CMOZ10V	CMOZ2V6	CMOZ30V	CMOZ6V2
CEN1235	CMOZ11L	CMOZ2V7	CMOZ33L	CMOZ6V8
CEN1235	CMOZ11V	CMOZ20L	CMOZ33V	CMOZ7L5
CEN1240	CMOZ12L	CMOZ20V	CMOZ36L	CMOZ7V5
CEN1240	CMOZ12V	CMOZ22L	CMOZ36V	CMOZ8L2
CEN1241	CMOZ13L	CMOZ22V	CMOZ39L	CMOZ8V2
CEN1241	CMOZ13V	CMOZ24L	CMOZ39V	CMOZ9L1
CEN1242	CMOZ15L	CMOZ24V	CMOZ4L3	CMOZ9V1
CEN1242	CMOZ15V	CMOZ27L	CMOZ4L7	CMO5V0LC
CMOD2004	CMOZ16L	CMOZ27V	CMOZ4V3	
CMOD2005	CMOZ16V	CMOZ3L0	CMOZ4V7	
CMOD3003	CMOZ18L	CMOZ3L3	CMOZ43L	
CMOD4448	CMOZ18V	CMOZ3L6	CMOZ43V	
CMOD6001	CMOZ18VC	CMOZ3L9	CMOZ47L	
CMOD6263	CMOZ2L0	CMOZ3V0	CMOZ5L1	
CMOSH-3	CMOZ2L2	CMOZ3V3	CMOZ5L6	
CMOSH-4E	CMOZ2L4	CMOZ3V6	CMOZ5V1	
CMOSH2-4L	CMOZ2L5	CMOZ3V9	CMOZ5V6	
CMOZ1L8	CMOZ2L7	CMOZ3V9C	CMOZ6L2	